

# Cleaner

## SLOTOCLEAN S 20

The Cleaner SLOTOCLEAN S 20 is primarily used for cleaning of printed circuit boards prior to activation.

SLOTOCLEAN S 20 removes films from the surface like fingerprints, oxidic layers and coupling agents from plating resists and thereby ensures fast action of the subsequent activation on the copper surface.

The Cleaner SLOTOCLEAN S 20 only slightly attacks copper surfaces (0.5 - 1 µm/h). No deposit layers will be formed on surfaces treated with Cleaner SLOTOCLEAN S 20.

The SLOTOCLEAN S 20 is based on sulphuric acid.

Tin may re-dissolve if jigs are used that have not been stripped thus resulting in cloud formation of the cleaner solution.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

### Important:

Please read these instructions carefully and follow recommendations given.

We reserve the right to make technical changes as necessary.

In the interests of safety, please pay attention to the R- and S- phrases on the drum label.

The shelf life of the additives is generally 18 months.

The date of production is taken from the first 3 figures of the batch number.

Figure 1 = year; figures 2-3 = month; figures 4-7 = batch number; (UK labels use a 4 digit year code).

For the storage of chemical products only the TRGS 514 and TRGS 515 Regulations must be followed. The Hazardous Goods Regulation (ADR/GGVS) are only valid for transportation and must not be applied to storage.

